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US 20060109588 A1	20060525	Method of making a perpendicular recording magnetic head pole tip with an etchable adhesion CMP stop layer	360/126		Le; Quang et al.
US 20060096612 A1	20060511	System and method for aligning wafers within wafer processing equipment	134/2	134/34; 134/94.1	Feng; Jian- Huei et al.
US 20060092564 A1	20060504	Method for manufacturing a stitched "floating" trailing shield for a perpendicular recording head	360/126		Le; Quang
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US 20060091559 A1	20060504	Hardmask for improved reliability of silicon based dielectrics	257/775	438/638; 438/790	Nguyen; Son Van et al.
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US 20060055004 A1	20060316	Low K and ultra low K SiCOH dielectric films and methods to form the same	257/632	257/E23.167	Gates; Stephen M. et al.
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20060036893		for debugging			Debbie Ann
Al	20060202	Ethernet	260/125		et al.
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US 20050237666 A1	20051027	Magnetic write head with recessed overcoat	360/126		Hsiao, Wen-Chien David et al.
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US	20050908	SiCOH dielectric	257/232	257/E31.057	Edelstein,
20050194619	20030700	material with	2511252	2577251.057	Daniel C. et
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Al					ai.
		and improved Si-C			
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		semiconductor device			
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		memory structure		438/95	
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A1		perpendicular			
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A1		fabrication			al.
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		the same			
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AI		through a mask			al.
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A1		magnetic recording			
		with a shield structure			
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		with single pole write			
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US 20050068669 A1	20050331	Head for perpendicular recording with a floating trailing shield	360/125		Hsu, Yimin et al.
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20030135987 A1		narrow pole tip by ion beam deposition		29/603.23	James Bernard et al.
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US 7022248 B2	20060404	Method for patterning a self-aligned coil using a damascene process	216/22	216/13; 216/17; 216/18; 216/88; 216/89; 29/603.01	Bedell; Daniel Wayne et al.
US 7014530 B2	20060321	Slider fabrication system for sliders with integrated electrical lapping guides	451/8	451/41	Kasiraj; Prakash et al.
US 7011890 B2	20060314	Modulated/composited CVD low-k films with improved mechanical and electrical properties for nanoelectronic devices	428/447	257/E21.261; 257/E21.277; 426/131; 427/101; 427/387; 427/470; 427/489; 427/494; 427/495; 427/508; 427/515; 427/595	Nguyen; Son Van et al.
US 7009812 B2	20060307	Magnetic transducer for perpendicular magnetic recording with single pole write head with trailing shield	360/126		Hsu; Yimin et al.
US 7002775 B2	20060221	Head for perpendicular	360/125		Hsu; Yimin et al.

US 6996894 B2	20060214	magnetic recording with a shield structure connected to the return pole piece Methods of making magnetic heads with improved contiguous junctions	29/603.12	204/192.34; 216/22; 216/40; 29/603.13; 29/603.15; 29/603.16; 29/603.18;	Hsiao; Richard et al.
US 6987646 B2	20060117	Method of making magnetic head having narrow pole tip and fine pitch coil	360/126	360/322 360/125	Hsiao; Richard et al.
US 6984579 B2	20060110	Ultra low k plasma CVD nanotube/spin- on dielectrics with improved properties for advanced nanoelectronic device fabrication	438/622	257/750; 257/758; 257/E21.576; 257/E21.581; 438/618; 977/890	Nguyen; Son Van et al.
US 6949200 B2	20050927	Planar magnetic head and fabrication method therefor	216/22	216/38; 216/39; 216/75; 29/603.07	Fontana; Robert E. et al.
US 6948231 B2	20050927	Method of depositing material into high aspect ratio features	29/603.25	216/62; 216/65; 216/66; 29/603.13; 29/603.14; 29/606; 360/122; 360/126; 360/317; 427/127; 427/128; 451/41; 451/5	Hsiao; Richard et al.
US 6944937 B2	20050920	Method of reducing ESD damage in thin film read heads which enables measurement of gap resistance	29/603.09	29/603.07; 29/603.11; 29/603.13; 29/603.14; 29/605; 29/606; 29/609;	Hsiao; Richard et al.

				324/309;	
				324/314;	
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				360/322;	
				360/323;	
				360/324;	
				427/127;	
				427/128;	
				451/41; 451/5	
US 6927940	20050809	Method for seed layer	360/126	360/123	Hsiao;
B2	2005000	removal for magnetic	300/120	300/123	Richard et
152		heads			al.
US 6919280	20050719	Method of removing	438/710	438/712;	Hsiao;
B2	20030713	magnetoresistive	150,710	438/722	Richard et
B2		sensor cap by reactive		130/122	al.
		ion etching			ai.
US 6913992	20050705	Method of modifying	438/628	257/E21.26;	Schmitt;
B2	20030703	interlayer adhesion	450/020	257/E21.277;	Francimar
52		interruyer demesion		257/E21.576;	Campana et
				257/E21.579;	al.
				438/622;	ui.
				1 730/022.	
i.				1	
				438/623;	
US 6013704	20050705	Magnetic head	216/22	438/623; 438/638	Heigo
US 6913704	20050705	Magnetic head	216/22	438/623; 438/638 216/52;	Hsiao;
US 6913704 B2	20050705	induction coil	216/22	438/623; 438/638 216/52; 216/67;	Richard et
i	20050705	induction coil fabrication method	216/22	438/623; 438/638 216/52; 216/67; 216/72;	1 ' 1
i	20050705	induction coil fabrication method utilizing aspect ratio	216/22	438/623; 438/638 216/52; 216/67; 216/72; 216/74;	Richard et
B2		induction coil fabrication method utilizing aspect ratio dependent etching		438/623; 438/638 216/52; 216/67; 216/72; 216/74; 216/75	Richard et al.
B2 US 6901653	20050705	induction coil fabrication method utilizing aspect ratio dependent etching Process for	216/22 29/603.25	438/623; 438/638 216/52; 216/67; 216/72; 216/74; 216/75 216/39;	Richard et al. Hsiao;
B2		induction coil fabrication method utilizing aspect ratio dependent etching Process for manufacturing a		438/623; 438/638 216/52; 216/67; 216/72; 216/74; 216/75 216/39; 216/47;	Richard et al. Hsiao; Richard et
B2 US 6901653		induction coil fabrication method utilizing aspect ratio dependent etching Process for manufacturing a magnetic head coil		438/623; 438/638 216/52; 216/67; 216/72; 216/74; 216/75 216/39; 216/47; 29/603.23;	Richard et al. Hsiao;
B2 US 6901653		induction coil fabrication method utilizing aspect ratio dependent etching Process for manufacturing a		438/623; 438/638 216/52; 216/67; 216/72; 216/74; 216/75 216/39; 216/47; 29/603.23; 29/606;	Richard et al. Hsiao; Richard et
B2 US 6901653		induction coil fabrication method utilizing aspect ratio dependent etching Process for manufacturing a magnetic head coil		438/623; 438/638 216/52; 216/67; 216/72; 216/74; 216/75 216/39; 216/47; 29/603.23; 29/606; 336/200;	Richard et al. Hsiao; Richard et
US 6901653 B2	20050607	induction coil fabrication method utilizing aspect ratio dependent etching Process for manufacturing a magnetic head coil structure	29/603.25	438/623; 438/638 216/52; 216/67; 216/72; 216/74; 216/75 216/39; 216/47; 29/603.23; 29/606; 336/200; 360/123	Richard et al. Hsiao; Richard et al.
US 6901653 B2 US 6878620		induction coil fabrication method utilizing aspect ratio dependent etching Process for manufacturing a magnetic head coil structure Side wall passivation		438/623; 438/638 216/52; 216/67; 216/72; 216/74; 216/75 216/39; 216/47; 29/603.23; 29/606; 336/200; 360/123 257/E21.576;	Richard et al. Hsiao; Richard et al. Nguyen;
US 6901653 B2	20050607	induction coil fabrication method utilizing aspect ratio dependent etching Process for manufacturing a magnetic head coil structure Side wall passivation films for damascene	29/603.25	438/623; 438/638 216/52; 216/67; 216/72; 216/74; 216/75 216/39; 216/47; 29/603.23; 29/606; 336/200; 360/123 257/E21.576; 257/E21.584;	Richard et al. Hsiao; Richard et al. Nguyen; Son Van et
US 6901653 B2 US 6878620	20050607	induction coil fabrication method utilizing aspect ratio dependent etching Process for manufacturing a magnetic head coil structure Side wall passivation films for damascene cu/low k electronic	29/603.25	438/623; 438/638 216/52; 216/67; 216/72; 216/74; 216/75 216/39; 216/47; 29/603.23; 29/606; 336/200; 360/123 257/E21.576; 257/E21.584; 438/634;	Richard et al. Hsiao; Richard et al. Nguyen;
US 6901653 B2 US 6878620	20050607	induction coil fabrication method utilizing aspect ratio dependent etching Process for manufacturing a magnetic head coil structure Side wall passivation films for damascene	29/603.25	438/623; 438/638 216/52; 216/67; 216/72; 216/74; 216/75 216/39; 216/47; 29/603.23; 29/606; 336/200; 360/123 257/E21.576; 257/E21.584;	Richard et al. Hsiao; Richard et al. Nguyen; Son Van et

				438/644	
US 6878240 B2	20050412	Apparatus and method for obtaining symmetrical junctions between a read sensor and hard bias layers	204/192.11	204/298.04; 204/298.15; 427/131	Bus- Kwofie; Raymond et al.
US 6873535 B1	20050329	Multiple width and/or thickness write line in MRAM	365/66	257/E21.665; 257/E27.005; 365/158; 365/171; 365/51; 365/63; 438/3	Lin; Wen Chin et al.
US 6870705 B2	20050322	Magnetic head having short pole yoke length and method for fabrication thereof	360/126	360/123	Hsiao; Richard et al.
US 6862798 B2	20050308	Method of making a narrow pole tip by ion beam deposition	29/603.13	204/192.15; 205/119; 205/122; 216/39; 216/41; 29/603.07; 29/603.15; 29/603.16; 29/603.18; 360/122; 360/126; 360/317; 427/127; 427/128	Kruger; James Bernard et al.
US 6859998 B2	20050301	Method of fabricating a narrow projection such as a write pole extending from a substrate	29/603.13	204/192.1; 204/192.11; 216/11; 216/22; 216/47; 29/603.12; 29/603.15; 29/DIG.16; 360/122; 360/125; 430/315; 430/320	Kruger; James et al.
US 6859347 B2	20050222	Magnetic transducer with electrically conductive shield for	360/319		Hsiao; Richard et al.

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		reducing electromagnetic interference			
US 6819527 B1	20041116	Magnetic head with lower coil traces connected to integrally formed vertical interconnects and upper coil traces through plural insulating layer arrangement	360/123	360/126	Dill; Frederick Hayes et al.
US 6804879 B2	20041019	Method of fabricating a magnetic transducer with a write head having a multi-layer coil	29/603.24	216/22; 216/47; 216/48; 216/87; 29/603.16; 29/603.23; 29/603.25; 360/119; 360/122; 360/123	Hsiao; Richard D. et al.
US 6804878 B1	20041019	Method of improving the reliability of magnetic head sensors by ion milling smoothing	29/603.12	204/192.34; 216/22; 216/52; 216/66; 29/603.15; 29/603.16; 29/603.18; 451/41	Campbell; Richard Thomas et al.
US 6801206 B2	20041005	Method and apparatus for virtualized operator panel	345/556	345/544; 711/153; 711/173	Poimboeuf; Joshua Nathan et al.
US 6795278 B2	20040921	Method of protecting read sensors from electrostatic discharge damage during the manufacture of magnetic heads	360/323		Jarrett; James Devereaux et al.
US 6792577 B1	20040914	Data distribution method and apparatus, and data receiving method and apparatus	715/522	380/255; 380/258; 705/50; 705/67; 705/71;	Kimoto; Yosuke

	1		1	715/512.	<u> </u>
				715/513; 715/523	
US 6785101 B2	20040831	Overlaid lead giant magnetoresistive head with side reading reduction	360/324.1		Webb; Patrick Rush et al.
US 6778433 B1	20040817	High programming efficiency MRAM cell structure	365/173	365/158; 365/171	Tang; Denny
US 6776917 B2	20040817	Chemical mechanical polishing thickness control in magnetic head fabrication	216/88	216/89; 216/94; 438/691; 438/692; 451/29	Hsiao; Richard et al.
US 6744607 B2	20040601	Exchange biased self- pinned spin valve sensor with recessed overlaid leads	360/322		Freitag; James Mac et al.
US 6741422 B2	20040525	Method of making magnetic head having narrow pole tip and fine pitch coil	360/126	29/603.15	Hsiao; Richard et al.
US 6723252 B1	20040420	Magnetic head P1 magnetic pole notching with reduced polymer deposition	216/22	216/37; 216/66; 216/75	Hsiao; Richard et al.
US 6711053 B1	20040323	Scaleable high performance magnetic random access memory cell and array	365/158	365/171; 365/173	Tang; Denny
US 6683136 B2	20040127	Epoxidized soybean oil enhanced hydrogenation of nitrile copolymer	525/329.3	524/464; 525/338; 525/339	Guo; Sharon X. et al.
US 6678127 B2	20040113	Device and method of reducing ESD damage in thin film read heads which enables measurement of gap resistances and method of making	360/323		Hsiao; Richard et al.
US 6664026 B2	20031216	Method of manufacturing high aspect ratio photolithographic features	430/311	216/72; 257/E21.035; 257/E21.044; 427/249.7; 430/313;	Nguyen; Son Van et al.

US 6655007 B2	20031202	Method of making a read sensor for a merged magnetic head	29/603.12	430/316; 430/317; 430/318; 438/702 204/192.34; 216/22; 216/66;	Hsiao; Richard
		with self-aligned low resistance leads		216/67; 29/603.07; 29/603.13; 29/603.18	
US 6650511 B2	20031118	Magnetic head assembly with electrostatic discharge (ESD) shunt/pads seed layer	360/323		Hsiao; Richard et al.
US 6646059 B2	20031111	Process for removing iron-and rhodium-containing catalyst residues from hydrogenated nitrile rubber	525/338	525/332.8; 525/332.9; 525/333.1; 525/333.2; 525/339; 525/351; 525/352	Nguyen; Paul et al.
US 6631546 B1	20031014	Self-aligned void filling for mushroomed plating	29/603.07	216/22; 216/49; 216/67; 29/846; 29/847; 427/96.2	Dinan; Thomas Edward et al.
US 6623652 B1	20030923	Reactive ion etching of the lapped trailing edge surface of a slider	216/22	216/67; 216/72; 216/80; 29/603.07	Hsiao; Richard et al.
US 6621660 B2	20030916	Thin film magnetic head	360/126	360/123	Hsiao; Richard et al.
US 6609948 B1	20030826	Method of making an electronic lapping guide (ELG) for lapping a read sensor	451/5	29/603.14; 29/603.16; 451/1; 451/11; 451/259; 451/28	Fontana, Jr.; Robert Edward et al.
US 6606263 B1	20030812	Non-disturbing programming scheme for magnetic RAM	365/158	365/171; 365/173	Tang; Denny
US 6602962	20030805	Process for the	525/338	525/329.3;	Nguyen;

B2		production of hydrogenated nitrile rubber		525/339	Paul et al.
US 6589436 B1	20030708	Method of adjusting the flatness of a slider using selective plasma etching	216/52	216/2; 216/22; 216/65; 216/66; 216/67; 219/121.69; 219/121.73; 29/603.12; 360/235.4; 360/318.1	Tabib; Jila et al.
US 6570739 B2	20030527	Magnetic head having write head element with high aspect ratio coil	360/123	360/317	Hsiao; Richard et al.
US 6516367 B1	20030204	Method and system for detecting bus device configuration changes	710/109	710/104; 713/2	Barenys; Michael Anton et al.
US 6515826 B1	20030204	Magnetic head induction coil fabrication method utilizing aspect ratio dependent etching	360/126	360/123	Hsiao; Richard et al.
US 6507456 B1	20030114	Dual coil and lead connections fabricated by image transfer and selective etch	360/123		Dinan; Thomas Edward et al.
US 6503406 B1	20030107	Method for forming the air bearing surface of a slider using nonreactive plasma	216/22	216/41; 216/49; 216/51; 216/67; 216/81; 29/603.15; 430/961	Hsiao; Yiping et al.
US 6495439 B1	20021217	Method for suppressing pattern distortion associated with BPSG reflow and integrated circuit chip formed thereby	438/597	257/E21.279; 257/E21.576; 257/E23.167; 438/602; 438/760; 438/763	Gambino; Jeffrey Peter et al.
US 6489255 B1	20021203	Low temperature/low dopant oxide glass film	438/784	257/E21.275; 438/632; 438/787;	Nguyen; Son Van et al.

				438/790	
US 6483172 B1	20021119	Semiconductor device structure with hydrogen-rich layer for facilitating passivation of surface states	257/639	257/640; 257/760; 257/E21.194; 257/E21.212; 257/E21.269; 257/E21.654	Cote; Donna Rizzone et al.
US 6477011 B1	20021105	Magnetic recording device having an improved slider	360/235.1		Hsiao; Richard et al.
US 6470566 B2	20021029	ESD protection during GMR head fabrication	29/603.13	29/603.07; 360/323	Hsiao; Richard et al.
US 6466408 B2	20021015	Storage system slider having trailing edge pad and method for making the same	360/235.7		Baumgart; Peter M. et al.
US 6437950 B1	20020820	Top spin valve sensor that has an iridium manganese (IrMn) pinning layer and an iridium manganese oxide (IrMnO) seed layer	360/324.11	360/324.12	Chau; Phong et al.
US 6416935 B1	20020709	Method for forming the air bearing surface of a slider	430/320	360/122	Hsiao; Yiping et al.
US 6399976 B1	20020604	Shrink-wrap collar for DRAM deep trenches	257/301	257/303; 257/306; 257/310; 257/311; 257/410; 257/443; 257/59; 257/72; 257/E21.396; 257/E21.651	Geiss; Peter John et al.
US 6379570 B1	20020430	Method of making high definition chevron type MR sensor	216/22	204/192.1; 216/41; 216/49; 29/603.01; 29/603.18	Fatula, Jr.; Joseph John et al.
US 6377423 B2	20020423	Planar stitched write head having write coil insulated with inorganic insulation	360/126		Dill, Jr.; Frederick Hayes et al.

US 6346183 B1	20020212	Use of thin carbon films as a bottom antireflective coating in manufacturing magnetic heads	205/119	204/192.2; 427/131	Baer; Amanda et al.
US 6338939 B1	20020115	Embedded dual coil fabrication process	430/320	29/603.14; 29/603.15; 29/603.18; 29/603.25; 430/314; 430/319	Clarke; Thomas Carl et al.
US 6328859 B1	20011211	Method of making second pole tip of a write head with a narrow track width	204/192.34	204/192.33	Hsiao; Richard et al.
US 6326794 B1	20011204	Method and apparatus for in-situ monitoring of ion energy distribution for endpoint detection via capacitance measurement	324/678	324/464	Lundquist; Paul Matthew et al.
US 6306266 B1	20011023	Method of making a top spin valve sensor with an in-situ formed seed layer structure for improving sensor performance	204/192.12	204/192.11	Metin; Serhat et al.
US 6239955 B1	20010529	Stabilized MR sensor and heat guide joined by contiguous junction	360/321		Dovek; Moris Musa et al.
US 6226149 B1	20010501	Planar stitched write head having write coil insulated with inorganic insulation	360/126	29/603.14	Dill, Jr.; Frederick Hayes et al.
US 6209193 B1	20010403	Method of making read sensor with self-aligned low resistance leads	29/603.15	216/22; 216/49; 216/66; 216/72; 29/603.11; 29/603.13; 29/603.18; 360/319; 360/320	Hsiao; Richard
US 6191918 B1	20010220	Embedded dual coil planar structure	360/126		Clarke; Thomas

					Carl et al.
US 6181532 B1	20010130	Stabilized MR sensor and flux/heat guide joined by contiguous junction	360/321	360/327.3	Dovek; Moris Musa et al.
US 6168845 B1	20010102	Patterned magnetic media and method of making the same using selective oxidation	428/836	204/192.2; 427/128; 427/130; 427/131; 427/250; 427/255.19; 427/255.4; 427/267; 427/269; 427/269; 427/282; 427/331; 427/398.4; 427/399; 427/405; 427/405; 427/405; 427/407.1; 427/409; 427/576; 427/576; 427/576; 427/595; 428/450; 428/450; 428/704; 428/704; 428/704; 428/900	Fontana, Jr.; Robert Edward et al.
US 6162582 A	20001219	Method of making a high resolution lead to shield short-resistant read head	430/312	360/320; 360/322; 430/315; 430/319	Hsiao; Richard et al.
US 6162305 A	20001219	Method of making spin valve read head with plasma produced metal oxide insulation layer between lead and shield layers	148/280	148/284; 148/DIG.117; 29/603.07	Hsiao; Richard et al.

US 6132813	20001017	High density plasma	427/490	427/127;	Chen; Pei
A		surface modification		427/309;	C. et al.
		for improving		427/491;	
		antiwetting properties		427/535;	
				427/536;	
				427/569	
US 6118623	20000912	High definition	360/320	360/313	Fatula, Jr.;
A		chevron type MR			Joseph John
		sensor			et al.
US 6074566	20000613	Thin film inductive	360/123	216/13;	Hsiao;
A		write head with		216/22;	Richard et
		minimal organic		216/27;	al.
		insulation material and		216/34;	
		method for its		216/49;	
		manufacture		252/79.1;	
1				252/79.4;	
			:	29/603.18;	
				360/122;	
				360/125;	
				360/126;	
				427/532;	
				427/534;	
				427/535;	
				427/548	
US 6069049	20000530	Shrink-wrap collar	438/386	257/E21.396;	Geiss; Peter
A		from DRAM deep		257/E21.651;	John et al.
		trenches		438/243;	
				438/248;	
				438/391	
US 6051099	20000418	Apparatus for	156/345.37	118/723E;	Bus-
A		achieving etch rate		118/724	Kwoffie;
		uniformity			Raymond et
110 (001 (0.7)	00000000		0.60/10.6	260/121	al.
US 6031695	20000229	Combined read head	360/126	360/121;	Hsiao;
A		and write head with		360/122;	Richard et
		non-magnetic		360/317	al.
		electrically conductive			
		layer on upper pole tip			
110 6007060	20000222	thereof	120/251	257/E21 016	Navers
US 6027968	20000222	Advanced damascene	438/254	257/E21.016;	Nguyen;
A		planar stack capacitor		257/E21.647	Son Van et
110 6007660	20000222	fabrication method	216/22	216/71	al.
US 6027660	20000222	Method of etching	216/22	216/71;	Hsiao;
A		ceramics of		216/76;	Richard et
		alumina/TiC with high		216/81	al.
		density plasma	<u> </u>		

US 6013583 A	20000111	Low temperature BPSG deposition process	438/783	257/E21.243; 257/E21.275; 438/787; 438/790	Ajmera; Atul C. et al.
US 6005944 A	19991221	System and method for constructing block ciphers	380/42		Blaze; Matthew A.
US 6004473 A	19991221	Magnetic write head having a coil with submicron pitch	216/22	216/72; 29/603.18	Hsiao; Richard et al.
US 6004256 A	19991221	Catalytic distillation oligomerization of vinyl monomers to make polymerizable vinyl monomer oligomers uses thereof and methods for same	585/517	508/503; 508/507; 508/508; 508/510	Townsend; Phillip et al.
US 6001268 A	19991214	Reactive ion etching of alumina/TiC substrates	216/67	216/74; 216/76; 216/77	Nguyen; Son Van et al.
US 5999379 A	19991207	Spin valve read head with plasma produced metal oxide insulation layer between lead and shield layers and method of making	360/320		Hsiao; Richard et al.
US 5994215 A	19991130	Method for suppression pattern distortion associated with BPSG reflow	438/624	257/760; 257/E21.576; 438/760	Gambino; Jeffrey Peter et al.
US 5978183 A	19991102	High resolution lead to shield short-resistant read head	360/320	360/322	Hsiao; Richard et al.
US 5973385 A	19991026	Method for suppressing pattern distortion associated with BPSG reflow and integrated circuit chip formed thereby	257/644	257/650; 257/760; 257/E21.279; 257/E21.576; 257/E23.167; 428/210	Gambino; Jeffrey Peter et al.
US 5930084 A	19990727	Stabilized MR sensor and flux guide joined by contiguous junction	360/321		Dovek; Moris Musa et al.
US 5901432 A	19990511	Method for making a thin film inductive write head having a pedestal pole tip and	29/603.14	205/122; 216/22; 29/603.15; 29/603.18	Armstrong; Michael et al.

		an electroplated gap			
US 5893981 A	19990413	Method of making stabilized MR sensor and flux guide joined by contiguous junction	216/22	216/41	Dovek; Moris Musa et al.
US 5885750 A	19990323	Tantalum adhesion layer and reactive-ion- etch process for providing a thin film metallization area	430/314	204/192.17; 204/192.2; 257/E21.535; 257/E21.589; 427/97.2; 427/97.4; 430/318	Hsiao; Richard et al.
US 5867890 A	19990209	Method for making a thin film merged magnetoresistive read/inductive write head having a pedestal pole tip	29/603.14	216/22; 29/603.15; 29/603.18; 360/317	Hsiao; Richard et al.
US 5855962 A	19990105	Flowable spin-on insulator	427/376.2	257/E21.271; 427/387; 427/58; 438/562; 438/918	Cote; Donna Rizzone et al.
US 5770469 A	19980623	Method for forming semiconductor structure using modulation doped silicate glasses	438/246	257/E21.278; 257/E21.576; 257/E23.118; 438/240; 438/424; 438/429; 438/982	Uram; Kevin J. et al.
US 5753948 A	19980519	Advanced damascene planar stack capacitor fabrication method	257/307	257/309; 257/310; 257/532; 257/E21.016; 257/E21.647	Nguyen; Son Van et al.
US 5714798 A	19980203	Selective deposition process	257/642	257/634; 257/702; 257/E21.259; 257/E21.549	Armacost; Michael David et al.
US 5648113 A	19970715	Aluminum oxide LPCVD system	427/8	427/126.4; 427/226; 427/248.1; 427/255.34	Barbee; Steven George et al.
US 5540777 A	19960730	Aluminum oxide LPCVD system	118/667	118/668; 118/708; 118/712;	Barbee; Steven G. et al.

				118/715; 118/719; 118/726	
US 5421507 A	19950606	Au-Sn transient liquid bonding in high performance laminates	228/194	228/195; 228/198	Davis; Charles R. et al.
US 5292688 A	19940308	Solder interconnection structure on organic substrates and process for making	29/840	257/E21.503; 257/E21.511; 257/E23.007; 257/E23.121; 29/841	Hsiao; Richard et al.
US 5280414 A	19940118	Au-Sn transient liquid bonding in high performance laminates	361/795	156/252; 174/255; 174/256; 174/257; 174/258; 29/830; 361/777; 361/778; 428/901	Davis; Charles R. et al.
US 5121190 A	19920609	Solder interconnection structure on organic substrates	257/778	228/180.1; 228/180.22; 257/786; 257/E21.503; 257/E21.511; 257/E23.007; 257/E23.121; 361/764; 361/765	Hsiao; Richard et al.